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Polymer surface modification by plasma reaction

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1. Introduction

Surface modification study of the polymer such as Acryl, PC and PET has been operated by various methodes(1) because of the wide industrial application. The plasma surface modification methode obtained by microwave has characteristics of short modification time and high vacuum pressure process and low price.

2. Experiment

The sputtering machine of batch type used in the our experiment has a maicrowave source and a cathode. The frequency of microwave is 2.45 GHz and gases used in the process are Ar and O_2 . The surface modification effects by plasma obtained from microwave(2) are estimated by contact angle and adhension test. Contact angles are measured by measurement system made by SEO. And the contace angle can be changed to the surface energy, The experiment are operated with variation of Ar, O_2 gases pressure ratio, pressure and microwave irradiation time etc. Adhension test is operated for Ti and Ti O_2 thin films coated on the polymer substrate irradiated by plasma.

3. Result

We measured the contact angle of polymers irradiated to plasma obtained by microwave in the range (170 sccm / 0 sccm ~ 70 sccm / 100sccm) of Ar/O₂ gas flow ratio . The surface energy of polymer has large tendency as O₂ gas flow is high. Polymers surface energy in the range of 1mtorr ~ 80mtorr is the highest in about $20\sim30$ mtorr and surface energy is independent of the gas flow ratio (O₂/Ar : $0\sim3$). We obtained the hysteresis curve of discharge voltage(3) when Ti target is sputtered reactively by using Ar and O₂ gas in dc magnetron methode. Excellent adhension of Ti thin film coated on the polymer modificated by plasma was obtained.

Reference

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